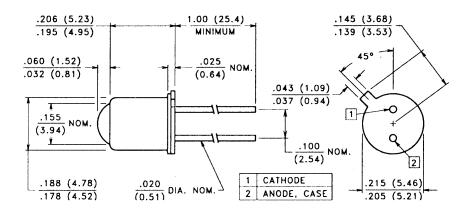
# **GaAs Infrared Emitting Diodes**

TO-46 Lensed Package — 940 nm

# VTE1113



### PACKAGE DIMENSIONS inch (mm)



CASE 24 TO-46 HERMETIC (Lensed) CHIP SIZE: .018" X .018"

#### **DESCRIPTION**

This narrow beam angle TO-46 hermetic emitter contains a large area, double wirebonded, GaAs, 940 nm IRED chip suitable for higher current pulse applications.

### ABSOLUTE MAXIMUM RATINGS @ 25°C (unless otherwise noted) ■

Maximum Temperatures		Maximum Reverse Voltage:	5.0V
Storage and Operating:	-55°C to 125°C	Maximum Reverse Current @ V <sub>R</sub> = 5V:	10 μΑ
Continuous Power Dissipation:	200 mW	Peak Wavelength (Typical):	940 nm
Derate above 30°C:	2.11 mW/°C	Junction Capacitance @ 0V, 1 MHz (Typ.):	35 pF
Maximum Continuous Current:	100 mA	Response Time @ $I_F = 20 \text{ mA}$	•
Derate above 30°C:	1.05 mA/°C	Rise:1.0 µs Fall: 1.0 µs	
Peak Forward Current, 10 µs, 100 pps:	3.0 A	Lead Soldering Temperature:	260°C
Temp. Coefficient of Power Output (Typ.):	8%/°C	(1.6 mm from case, 5 seconds max.	

(1.6 min from case, 5 seconds max

## ELECTRO-OPTICAL CHARACTERISTICS @ 25°C (See also GaAIAs curves, pages 123-124)

Part Number	Output					Forwar	d Drop	Half Power Beam		
	Irradiance			Radiant Intensity	Total Power	Test Current	V	F	Angle	
	E <sub>e</sub> Condit		dition	I <sub>e</sub>	P <sub>O</sub>	I <sub>FT</sub>	@	I <sub>FT</sub>	θ <sub>1/2</sub>	
	mW/cm <sup>2</sup>		distance	Diameter	mW/sr	mW	mA	Volts		Tun
	Min.	Тур.	mm	mm	Min.	Тур.	(Pulsed)	Тур.	Max.	Тур.
VTE1113	12	15	36	6.4	156	30	1.0	1.9	2.5	±10°

■ Refer to General Product Notes, page 2.